# 2SD2249

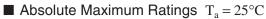
# Silicon NPN epitaxial planar type

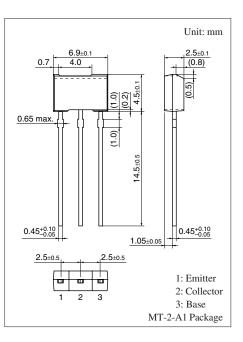
For low-frequency power amplification

### Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Satisfactory operation performances at high efficiency with the low-voltage power supply.
- Allowing supply with the radial taping

Parameter	Symbol	Rating	Unit			
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	40	V			
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V			
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	7	V			
Collector current	I <sub>C</sub>	5	А			
Peak collector current	I <sub>CP</sub>	8	А			
Collector power dissipation *	P <sub>C</sub>	1	W			
Junction temperature	Tj	150	°C			
Storage temperature	T <sub>stg</sub>	-55 to +150	°C			





Note) \*: Printed circuit board: Copper foil area of 1 cm<sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portion

## Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

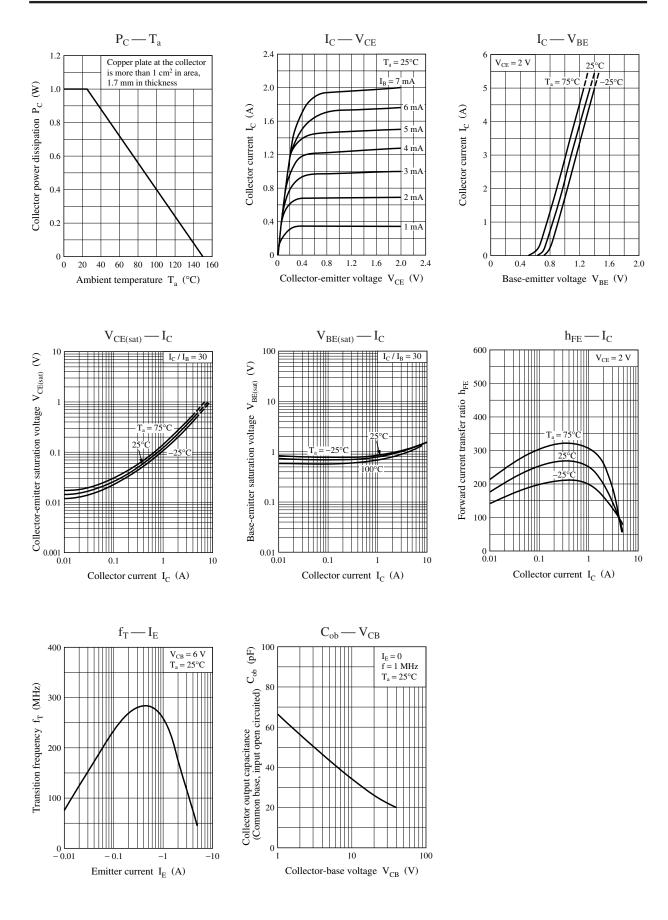
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = 1  {\rm mA},  I_{\rm B} = 0$	20			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$	7			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 10 \text{ V}, I_E = 0$			0.1	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 7 V, I_C = 0$			0.1	μΑ
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = 2 V, I_C = 0.5 A$	230		600	
	h <sub>FE2</sub>	$V_{CE} = 2 V, I_C = 2 A$	150			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_{\rm C} = 3 \text{ A}, I_{\rm B} = 0.1 \text{ A}$		0.3	1.0	V
Transition frequency *1	f <sub>T</sub>	$V_{CB} = 6 V, I_E = -50 mA, f = 200 MHz$		150		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			50	pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. \*1: Pulse measurement

\*2: Rank classification

Rank	R	S
h <sub>FE1</sub>	230 to 380	340 to 600

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